/ Revised record

版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
			与刘哥确认功率　　由 625 mW 改为 300mW	黄超	刘晓荣

/ Descriptions

塑封封装　　半导体三极管。Silicon PNP transistor in a SOT-23 Plastic Package.

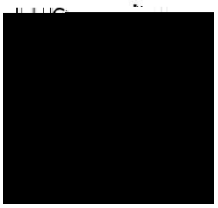
/ Features

与　　互补。
Complementary pair with L8050M.

/ Applications

功率放大电路。
Power amplifier applications.

/ Equivalent Circuit



/ Pinning

PIN1：Base　　PIN 2： Emitter　　PIN 3：Collector

/ h_{FE} Classifications & Marking

h_{FE}

h

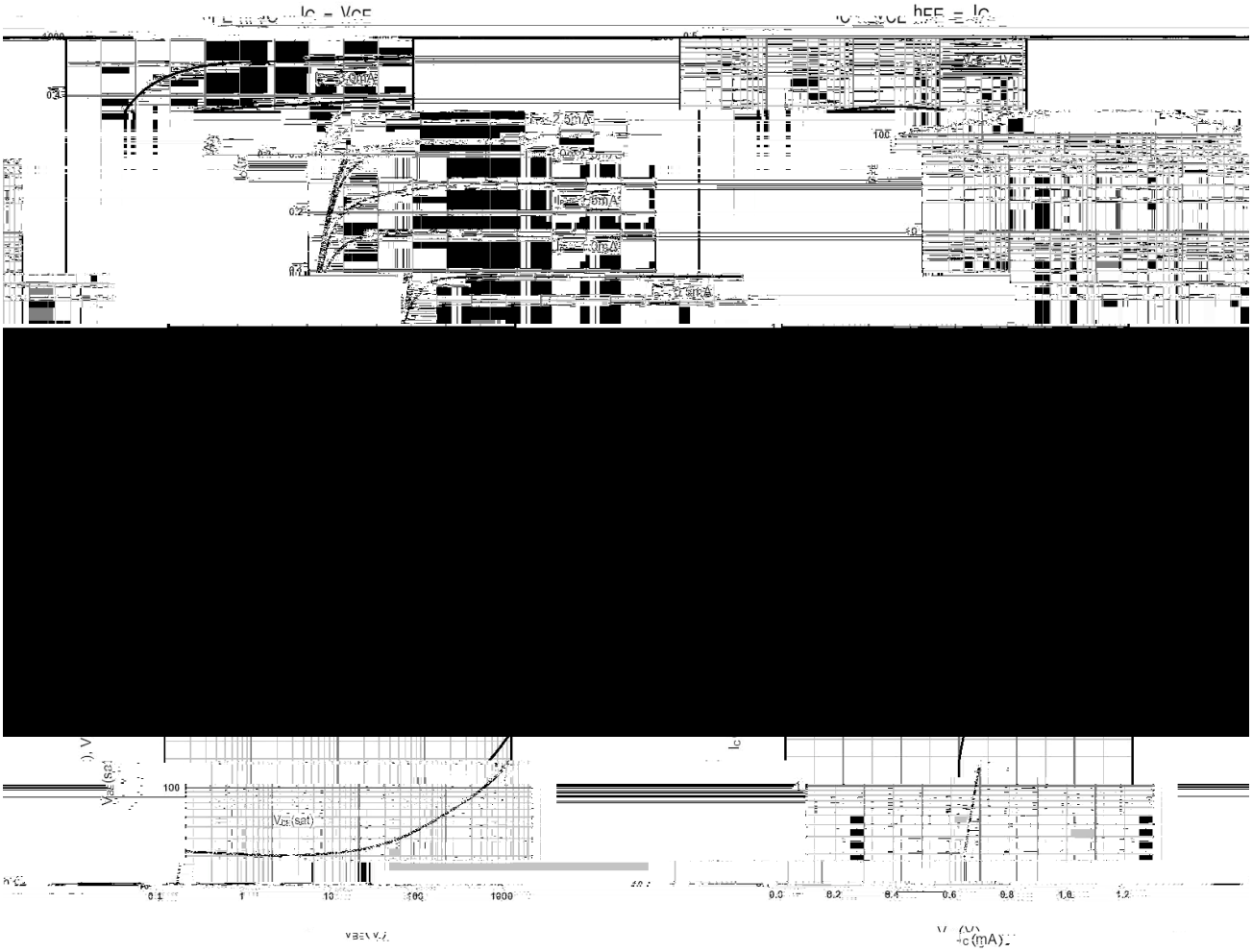
/ Absolute Maximum Ratings(Ta=25)

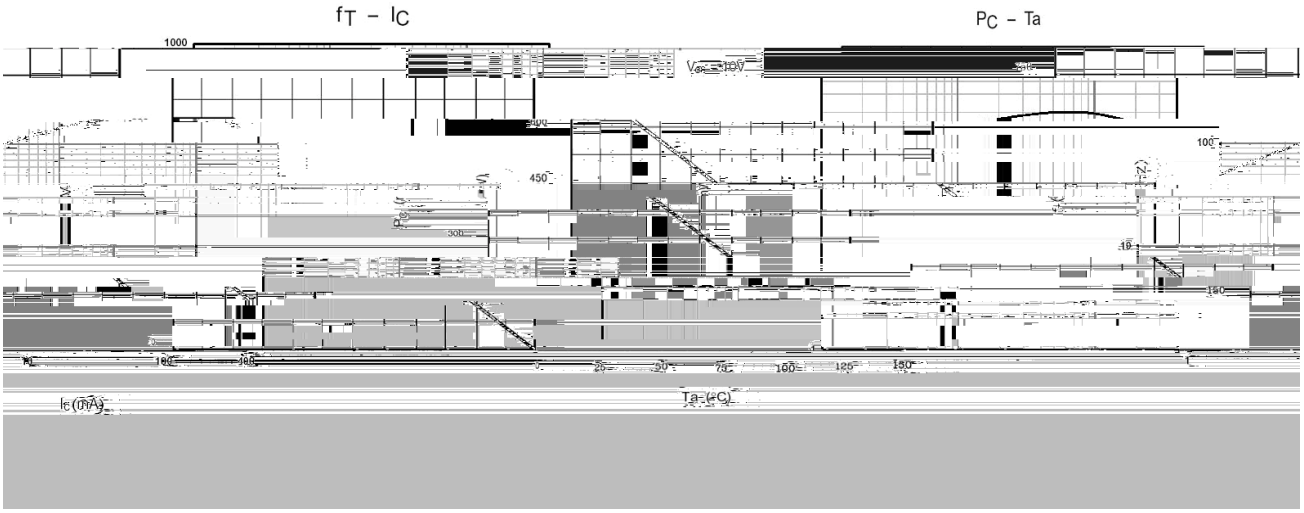
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	-30	V
Collector to Emitter Voltage	V_{CEO}	-20	V
Emitter to Base Voltage	V_{EBO}	-6.0	V
Collector Current - Continuous	I_C	-1.5	A
Base Current - Continuous	I_B	-0.5	A
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	℃
Storage Temperature Range	T_{stg}	-55～150	℃

/ Electrical Characteristics(Ta=25)

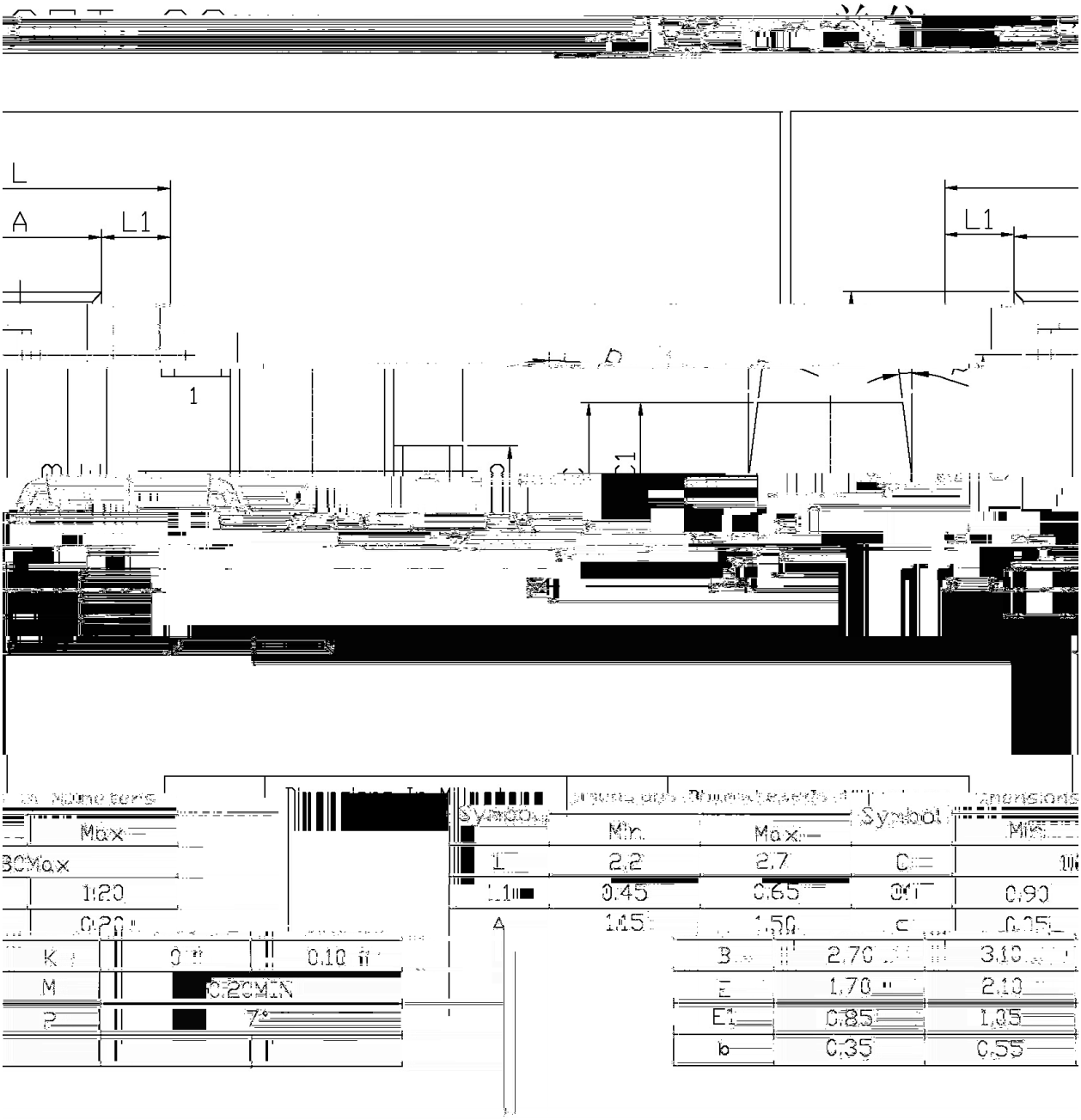
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	I_C=-0.1mA I_E=0	-30			V
Collector to Emitter Breakdown Voltage	V_{CEO}	I_C=-2.0mA I_B=0	-20			V
Emitter to Base Breakdown Voltage	V_{EBO}	I_E=-0.1mA I_C=0	-6.0			V
Collector Cut-Off Current	I_{CBO}	V_{CB}=-30V I_E=0			-0.1	μA
Emitter Cut-Off Current	I_{EBO}	V_{EB}=-6.0V I_C=0			-0.1	μA
DC Current Gain	$h_{FE(1)}$	V_{CE}=-1.0V I_C=-100mA	85		300	
	$h_{FE(2)}$	V_{CE}=-1.0V I_C=-800mA	40			
	$h_{FE(3)}$	V_{CE}=-1.0V I_C=-5.0mA	45			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=-800mA I_B=-80mA		-0.28	-0.5	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	I_C=-800mA I_B=-80mA		-0.98	-1.2	V
Base to Emitter Saturation Voltage	V_{BE}	V_{CE}=-1.0V I_C=-10mA		-0.66	-1.0	V
Transition Frequency	f_T	V_{CE}=-10V I_C=-50mA	100	200		MHz
Collector Output Capacitance	C_{ob}	V_{CB}=-10V I_E=0 f=1.0MHz		15		pF

/ Electrical Characteristic Curve

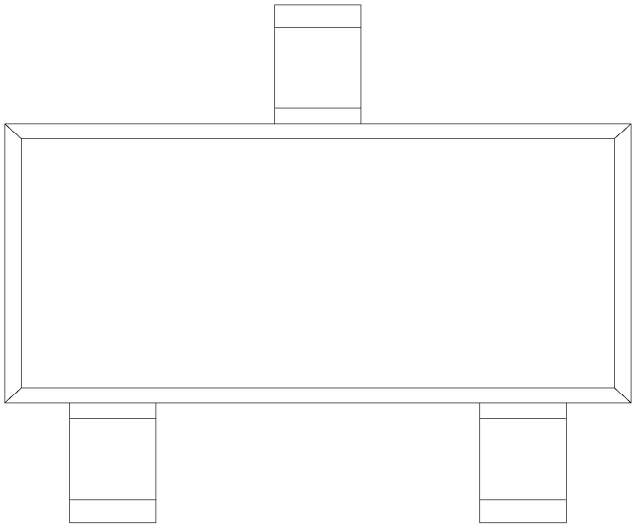




/ Package Dimensions



/ Marking Instructions



说明：

H： 为公司代码

Y2： 为型号代码

B： 为 h_{FE} 分档代码

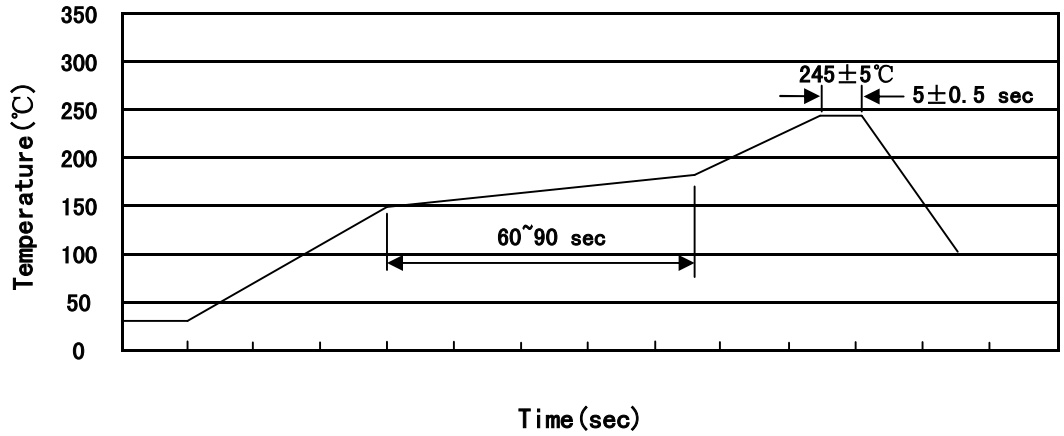
Note:

H: Company Code

Y2: Product Type Code

B: h_{FE}

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

1、预热温度 150～180℃，时间 60～90sec;

2、峰值温度 245±5℃，时间持续为 5±0.5sec;

3、焊接制程冷却速度为 2～10℃/sec.

Note:

1.Preheating:150~180℃, Time:60~90sec.

2.Peak Temp.:245±5℃, Duration:5±0.5sec.

3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃ 时间：10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type	Units					Dimension		(unit mm^3)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

/ Notices